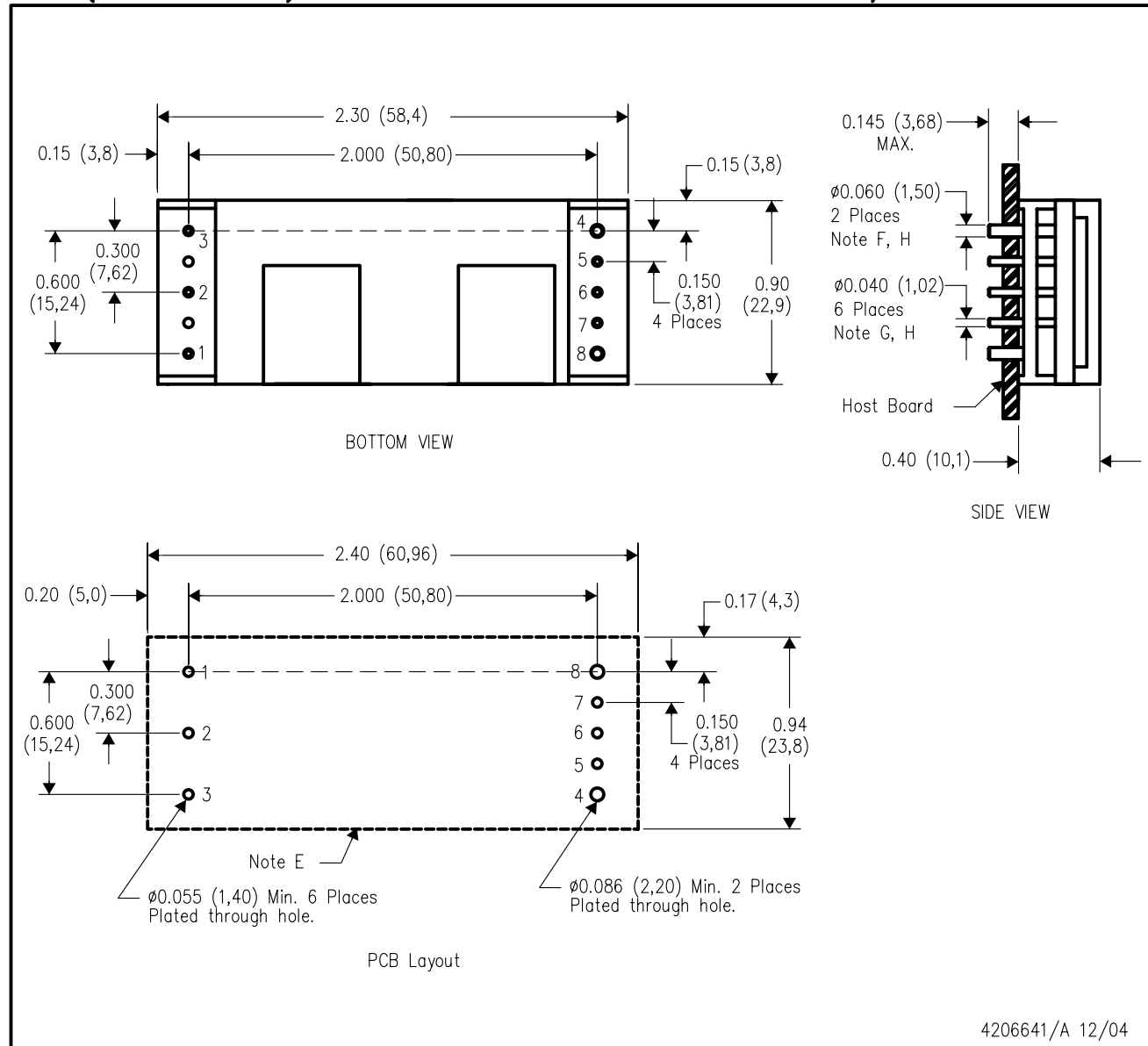


EQJ (R-PDSS-T8)

1/8 BRICK MODULE



- NOTES:
- A. All linear dimensions are in inches (mm).
 - B. This drawing is subject to change without notice.
 - C. 2 place decimals are ± 0.020 ($\pm 0,51$ mm).
 - D. 3 place decimals are ± 0.010 ($\pm 0,25$ mm).
 - E. Recommended keep out area for user components.

- F. Pins are 0.060" (1,50) diameter with 0.125" (3,20) diameter standoff shoulder.
- G. Pins are 0.040" (1,02) diameter.
- H. All pins: Material – Copper Alloy
Finish – Tin (100%) over Nickel plate

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